

**Amendment of Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (currently amended) A die pad configuration for an integrated circuit having an integrated circuit die, the die pad configuration comprising:

four separate and isolated die pad regions, each of said die pad regions under one of the four corners of said integrated circuit die and in contact with said integrated circuit die.

2. (cancelled)

3. (previously presented) The die pad configuration of claim 1 wherein the ratio of the total area of the four die pad regions to the die area is in the range of about 0.3 to about 0.5.

4. (previously presented) The die pad configuration of claim 3 wherein the ratio is about 0.32.

5 - 7. (cancelled)

8. (currently amended) A die pad for an integrated circuit having an integrated circuit die, the die pad comprising a support portion for supporting the integrated circuit die, the support portion supporting substantially all of said integrated circuit die, except that corner regions of said die are not supported by said support portion and where the support portion of the die pad has a cross shape under the integrated circuit die resulting from the support portion having rectangular cutouts below the corner regions.

9. (previously presented) The die pad of claim 8, wherein the ratio of the area of the support portion of the die pad to the area of the die is in the range of about 0.3 to about 0.5.

10 -15. (cancelled)